

TI-31729

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N THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Guoqiang Xing, et al.

Serial No:

09/901,416

Examiner:

Thanh T. Nguyen

Filed:

07/09/2001

DUAL HARDMASK PROCESS FOR THE FORMATION OF COPPER/LOW-K **INTERCONNECTS**

AMENDMENT PURSUANT TO 37 CFR 1.116

Mail Stop AF Commissioner For Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA

Docket No:

Conf. No:

Art Unit:

Responsive to the Office Action mailed March 24, 2003, in connection with the above identified application, Applicants respectfully submit the following remarks.

TECHNOLOGY CENTER 2800